

AMENDMENTS TO THE CLAIMS

1. (original) A liquid epoxy resin composition comprising

(A) a liquid epoxy resin,

(B) an aromatic amine curing agent having a phenolic hydroxyl group in a skeleton, and

(C) an inorganic filler.

2. (original) The composition of claim 1, further comprising a silicone-modified resin in the form of a copolymer which is obtained from an alkenyl group-containing epoxy resin or phenolic resin and an organopolysiloxane having the average compositional formula (6):



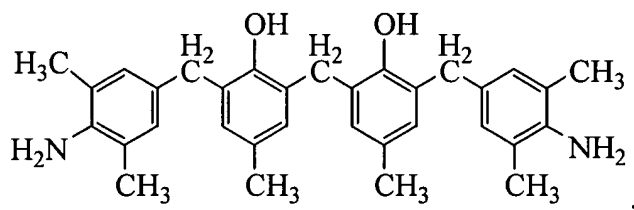
wherein R^5 is a substituted or unsubstituted monovalent hydrocarbon group, "a" is a number of 0.01 to 0.1, "b" is a number of 1.8 to 2.2, and $1.81 \leq a+b \leq 2.3$, said organopolysiloxane containing per molecule 20 to 400 silicon atoms and 1 to 5 hydrogen atoms each directly attached to a silicon atom (i.e., SiH groups), by effecting addition reaction between alkenyl groups and SiH groups.

3. (original) A semiconductor device which is encapsulated with the liquid epoxy resin composition of claim 1 in the cured state.

4. (original) A flip chip type semiconductor device which is encapsulated with the liquid epoxy resin composition of claim 1 in the cured state as an underfill.

5. (new) The liquid epoxy resin composition of claim 1, wherein
 component (A) is bisphenol F-type epoxy resin,
 component (B) is tetraethyldiaminophenylmethane, and
 component (C) is spherical silica.

6. (new) The liquid epoxy resin composition of claim 5, further comprising a diamine of the formula



phenyl glycidyl ether, γ -glycidoxypropyltrimethoxysilane, and a copolymer addition reaction product of

